

Welcome and Orientation

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ESSDERC/ ESSCIRC Workshop “Process Variations from Equipment
Effects to Circuit and Design Impacts”

September 3, 2018, Dresden, Germany

Slide 1



SUPERAID7 Workshop “Process
Variations from Equipment Effects to
Circuit and Design Impacts”
September 3, 2018, Dresden



H2020 Project SUPERAID7 Stability Under Process Variability for Advanced Interconnects and Developed Beyond 7 nm node

- Funded by EC within the H2020 Programme
- Duration 01/2016-12/2018
- Overall funding 3377527.50 Euros, 363 PM
- Successor of FP7 project SUPERAID7 (10/2012 – 12/2015)
- Consortium of 2 research institutes, 2 universities, 1 software house



July 1, 2017 replaced by



Slide 2



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Workshop Agenda

- This orientation
 - Overview of SUPERAID7 project
 - Keynote from member of Industrial and Scientific Advisory Board
 - Seven presentations on key technical activities in SUPERAID7
 - Summary and open discussion
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- Copies of presentations (partly shortened) distributed at the beginning of the workshop

Slide 3



SUPERAID7 Workshop "Process Variations from Equipment Effects to Circuit and Design Impacts" September 3, 2018, Dresden



Workshop Agenda

- 9:00 Registration
- 9:15 Welcome and orientation
J. Lorenz, Fraunhofer IISB
- 9:30 Process variability and the SUPERAID7 approach
J. Lorenz, Fraunhofer IISB
- 10:00-10:30 Coffee break
- 10:30 Statistical variability analysis in 28nm UTBB FDSOI devices
A. Juge, STMicroelectronics
- 11:00 Variability-aware topography simulation
E. Bär, Fraunhofer IISB
- 11:30 Physical models for nanowire device simulation
V. Georgiev, University of Glasgow
- 12:00 Simulation of nanoscale interconnects
L. Filipovic, TU Wien
- 12:30-14:00 Lunch
- 14:00 Variability-aware simulation of nanoscale devices
A. Asenov, V. Georgiev, University of Glasgow
- 14:30 LETI-NSP: Advanced compact models for nanowire devices
O. Rozeau, CEA/Leti
- 15:00 Simulation tools for DTCO of advanced technology nodes
C. Millar, Synopsys
- 15:30 3D devices: experiments and simulation
S. Barraud, CEA/Leti
- 16:00-16:30 Summary, open discussion and coffee break

Updated status as of August 1, 2018

Slide 4



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